

ABSTRACT OF THE DISCLOSURE

The invention relates to a method for making microcomponents which exhibit microreliefs, in a substrate (62), consisting of:

- 5 - a first step for making the desired microrelief (70, 72, 74) by mechanically machining the substrate and
- simultaneously with the first step, or after the latter, a second step for cutting out the microcomponents in the substrate.

Fig. 5B